

In the Claims

Claim 1 (currently amended): A semiconductor package comprising a solder having an alpha flux of less than ~~0.004~~ 0.0005 cts/cm²/hr.

Claim 2 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Ag, Bi, Cu, In, Pb or Sn.

Claim 3 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Ag.

Claim 4 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Sn.

Claim 5 (original): The semiconductor package of claim 1 wherein the solder is substantially lead-free.

Claim 6 (original): The semiconductor package of claim 1 wherein the solder is lead-containing solder that is at least 99 weight% lead.

Claim 7 (currently amended): The semiconductor package of claim 1 wherein the solder predominately comprises Bi, Cu or In ~~6 wherein the lead-containing solder has an alpha flux of less than 0.0005 cts/cm²/hr.~~

Claim 8 (currently amended): The semiconductor package of claim ~~6~~ 1 wherein the ~~lead-containing~~ solder has an alpha flux of less than 0.0002 cts/cm²/hr.

Claim 9 (currently amended): The semiconductor package of claim ~~6~~ 1 wherein the ~~lead-containing~~ solder has an alpha flux of less than 0.0001 cts/cm²/hr.

Claims 10-29 (canceled).